

SOLDERING TECHNOLOGY LABORATORY

LABORATORY INFORMATION FACT SHEET

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The Soldering Technology Laboratory (STL) is a dedicated Quality Engineering & System Assurance (QESA) facility established to provide inspection of the soldered connections of circuit boards and components for the Telemetry hardware and other DEVCOM weapon systems.

TECHNOLOGY/FACILITY DESCRIPTION:

All inspection criteria is based on IPC Standards (J-STD-001,IPC-A-610, 620 and 620B). The STL greatly enhances the reliability and repeatability of

the soldering process. The design and function of the inspection system is ideal for board manufacturing, rework, and replacement of components. The STL also supports malfunction investigations (i.e. short circuit) and other customer inquiries.



EQUIPMENT AND EXPERTISE AVAILABLE:

- Glenbrook Technologies X-ray Machines
- Carl Zeiss SV8 microscope with stand and illuminator
 Soldering inspection on (un)populated circuit boards,
- ball grid array, and wire assemblies
- IPC certified inspectors